

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|---|---|------------------|---------|------------------|
| S1 | 1 | 10/059907 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/15 15:17 |
| S4 | 2 | "6368475".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/15 15:19 |
| S5 | 3 | ("4391694" "5904827" "6126798").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/15 15:24 |
| S7 | 32574 | ("204" "205").clas. and (electroplating or plating or processing) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 15:54 |
| S8 | 8782 | S7 and (wafer or semiconductor or microelectronic) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/15 15:25 |
| S9 | 93 | S8 and diffuser and membrane | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/15 16:23 |
| S10 | 819 | S8 and diffus\$4 and membrane | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/15 15:26 |
| S11 | 8 | S8 and diffuser and membrane and pressure adj drop | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/15 16:23 |
| S12 | 17 | S8 and diffuser and membrane and pressure adj (drop or differen\$4) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 14:51 |
| S13 | 1 | "6258220".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 13:07 |
| S14 | 2042 | applied material and seal and (filter or diffus\$4) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2005/11/16 13:08 |
| S15 | 446 | S14 and (electroplating or plating or (electrochemical processing)) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2005/11/16 13:09 |
| S16 | 391 | S15 and (semiconductor or wafer or workpiece) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2005/11/16 13:09 |

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|-----|--------|---|------------------------|----|----|------------------|
| S17 | 154393 | electroplating or plating or (electrochemical adj processing) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 14:51 |
| S18 | 47947 | S17 and (semiconductor or wafer or microelectronic\$2) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 14:52 |
| S19 | 229 | S18 and (distribut\$4 or diffus\$4) and seal\$4 and membrane and conical | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 15:10 |
| S20 | 204 | S18 and ((distribut\$4 or diffus\$4) or membrane) same conical | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 15:55 |
| S21 | 152 | S20 not S19 | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 15:11 |
| S23 | 19960 | ("204" "205").clas. and (electroplating or plating) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 15:59 |
| S24 | 126 | S23 and ((distribut\$4 or diffus\$4) or membrane) same conical | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 16:01 |
| S25 | 71 | S24 not (S19 or S20) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 15:56 |
| S26 | 5023 | ("204" "205").clas. and (semiconductor or wafer or workpiece) and (plating or electroplating) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 16:01 |
| S27 | 61 | S26 and ((distribut\$4 or diffus\$4) or membrane) same conical | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 16:08 |
| S28 | 531 | S26 and ((distribut\$4 or diffus\$4) and membrane) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 17:12 |
| S30 | 68 | S28 and pressure adj (drop or differen\$5) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 16:17 |
| S31 | 1 | "6527920".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 16:17 |
| S32 | 20 | ("6126798").URPN. | USPAT | OR | ON | 2005/11/16 16:34 |
| S33 | 1 | "6261426".pn. | USPAT | OR | ON | 2005/11/16 16:34 |

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| S34 | 51 | ("3962047" "4137867" "4170959" "4246088" "4259166" "4280882" "4304641" "4339297" "4341613" "4466864" "4469566" "4534832" "4565607" "4597836" "4696729" "4828654" "4861452" "4879007" "4906346" "4931149" "5000827" "5024746" "5078852" "5096550" "5135636" "5222310" "5227041" "5332487" "5372699" "5377708" "5391285" "5405518" "5421987" "5429733" "5437777" "5441629" "5443707" "5447615" "5462649" "5472592" "5498325" "5522975" "5597460" "5670034" "5725745" "5750014" "5776327" "5788829" "5804052" "5843296" "5855850").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 16:37 |
| S35 | 201 | S26 and ((distribut\$4 or diffus\$4) same seal) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 17:46 |
| S36 | 1 | "6416647".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 17:17 |
| S37 | 4 | 09/351864 | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 17:45 |
| S38 | 165 | S35 not semitool.as. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 17:46 |
| S39 | 137 | S38 not (applied materials).as. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2005/11/16 18:02 |
| S40 | 1 | "6402923".pn. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2005/11/16 17:58 |
| S41 | 7 | ("3437578" "4469566" "5804052" "6033540" "6132805" "6179983").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 17:59 |
| S42 | 4 | ("20020000380" "20020008037" "6193860" "6497801").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/16 18:01 |

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| S43 | 776 | (steven near2 mayer) or (Novellus Systems) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2005/11/16 18:03 |
| S44 | 227 | S43 and plating | US-PGPUB; USPAT; USOCR | ADJ | ON | 2005/11/16 18:03 |
| S45 | 275 | S43 and (plating or electroplating) and (semiconductor or wafer) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2005/11/16 18:14 |
| S47 | 18138 | (plating or electroplating) and (semiconductor or wafer or workpiece or microelectronic\$2) | EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2005/11/16 18:14 |
| S48 | 1154 | S47 and (diffus\$4 or distribut\$4) | EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2005/11/16 18:21 |
| S49 | 60 | S48 and seal\$4 | EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2005/11/16 18:18 |
| S50 | 10 | S48 and membrane | EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2005/11/16 18:18 |
| S51 | 10 | S47 and diffuser | EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2005/11/16 18:19 |
| S52 | 795 | S47 and diffus\$4 | EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2005/11/16 18:22 |
| S53 | 0 | S47 and diffus\$4 near4 porous | EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2005/11/16 18:22 |
| S54 | 182 | S47 and membrane | EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2005/11/16 18:22 |
| S55 | 154579 | electroplating or plating or (electrochemical adj processing) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/17 10:02 |
| S56 | 48040 | S55 and (semiconductor or wafer or microelectronic\$2) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/17 10:02 |
| S57 | 229 | S56 and (distribut\$4 or diffus\$4) and seal\$4 and membrane and conical | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/17 10:03 |
| S58 | 1927 | S56 and (distribut\$4 or diffus\$4) same seal\$4 | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/17 10:04 |
| S60 | 107 | S58 and diffuser | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/17 10:05 |

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| S61 | 114 | S58 and (diffuser or (diffusion adj member)) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/17 10:30 |
| S62 | 396 | S58 and baffle | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/17 10:34 |
| S63 | 35 | S58 and baffle same seal | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/17 10:30 |
| S65 | 35 | S58 and baffle same (seal or shield) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/17 10:31 |
| S66 | 18 | S62 and ("204" "205").clas. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/17 10:34 |
| S67 | 4 | ("6442997" "6251251").pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/17 11:10 |
| S68 | 193 | cyprian near2 uzoh | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/17 11:11 |
| S69 | 99 | cyprian near2 uzoh | USPAT | OR | ON | 2005/11/17 11:20 |
| S71 | 19 | S69 and (filter or membrane) | USPAT | OR | ON | 2005/11/17 11:23 |
| S73 | 2 | "6126798".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/17 11:41 |